

000 001 TEPO: A TRANSFERABLE EDA PREDICTION 002 METHOD BASED ON LEARNGENE CHARACTERIZA- 003 004 005 006 007 008 009 010 011 012 013 014 015 016 017 018 019 020 021 022 023 024 025 026 027 028 029 030 031 032 033 034 035 036 037 038 039 040 041 042 043 044 045 046 047 048 049 050 051 052 053 TEPO: A TRANSFERABLE EDA PREDICTION METHOD BASED ON LEARNGENE CHARACTERIZATION

Anonymous authors

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ABSTRACT

This paper introduces TEPO, a novel multi-task learning framework to optimize Electronic Design Automation (EDA) in integrated circuit (IC) design by addressing increasing complexity and the limitations of traditional independent design task approaches. TEPO systematically decomposes design knowledge into gene knowledge and class knowledge, referred to as Learngenes. The framework employs a dual-pathway architecture with an adaptive gating mechanism, enabling fine-grained control over knowledge activation and enhancing computational efficiency and interpretability. The VIT-GNN fusion processor integrates Vision Transformer (ViT) features from layout images with Graph Neural Network (GNN) features from circuit topology, spatially aligning them onto a unified 256×256 grid to preserve both global visual patterns and local structural relationships. Our approach tackles four critical challenges in EDA: knowledge fragmentation, feature integration, transferability, and data scarcity. The methodology involves pre-training an upstream model to extract Learngene, which initializes a downstream 12-layer Transformer model for various prediction tasks. Experiments are conducted on CircuitNet-N28, a dataset providing multi-modal features for Congestion, DRC violations, IR-drop, and a new thermal prediction task. TEPO demonstrates strong transferability, faster convergence, reduced data requirements, and lower computational costs while achieving superior performance.

1 INTRODUCTION

Electronic Design Automation (EDA) faces growing complexity as modern ICs require simultaneous optimization of Performance, Power, and Area (PPA) (Wang, 2016). Since PPA metrics are only available post-layout (Kawa et al., 2006; Lavagno et al., 2018), long iteration cycles hinder design efficiency. Early prediction of these metrics is critical for rapid defect identification, motivating the use of neural networks in EDA (Knechtel et al., 2020; Yu, 2023; Goswami & Bhatia, 2023). However, existing methods treat tasks in isolation, failing to exploit shared design patterns across stages (Shrestha & Savidis, 2024).

We propose **TEPO**, a transferable EDA optimization framework that decomposes knowledge into *gene knowledge* (universal IC design patterns) and *class knowledge* (task-specific expertise). This separation enables effective knowledge sharing and rapid adaptation to new tasks. TEPO features a dual-pathway architecture with matrix decomposition and adaptive gating: gene gates (σ_{gene}) regulate universal patterns, while class gates ($\sigma_{class} \odot g_{task}$) route task-specific knowledge, enhancing both efficiency and interpretability.

To integrate multi-modal inputs, we introduce a VIT-GNN fusion processor that combines layout features from Vision Transformers (ViT) with topology representations from Graph Neural Networks (GNNs). By aligning ViT patches and GNN nodes on a unified 256×256 spatial grid via nearest-neighbor mapping, our fusion preserves global visual structures and local connectivity.

Our key contributions are:

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1. **Knowledge Decomposition for EDA:** We present the first framework to explicitly separate universal and task-specific knowledge in EDA via weight matrix decomposition $W_{\text{effective}} = W_{\text{gene}} + W_{\text{class}}$, addressing knowledge fragmentation.
2. **Multi-Modal Fusion:** The VIT-GNN processor bridges layout-image and circuit-graph modalities through spatial alignment, enabling comprehensive feature integration.
3. **Adaptive Knowledge Routing:** A dual-level gating mechanism allows fine-grained control over knowledge activation, improving flexibility and interpretability.
4. **Transferable Optimization:** TEPO achieves fast convergence and reduced data needs in both known and novel tasks by inheriting gene knowledge, demonstrating strong transferability under data scarcity.

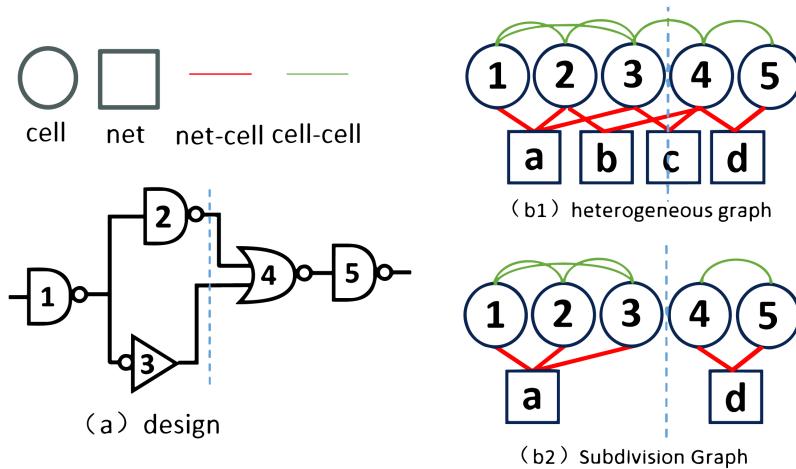


Figure 1: Heterogeneous graph construction and feature extraction for GNNs.

2 RELATED WORK

2.1 EARLY STAGE PREDICTION

For modern Electronic Design Automation (EDA), the design flow is characterized by its extensive chain and the difficulty of isolated point optimization (Dong et al., 2023). The key PPA metrics (Power, Performance, Area) that evaluate chip quality are only obtainable after the entire flow completes, leading to long iteration cycles. Therefore, Early Stage Prediction of final performance metrics is crucial for identifying potential defects early on (Ren & Hu, 2022; Kahng, 2022). This primarily includes:

- **Congestion Prediction:** This involves anticipating areas within the chip that are likely to experience routing resource shortages when numerous signal lines need to pass through a restricted area (Kirby et al., 2019). Prediction is based on netlist information, the placement of standard cells and macros, and the availability of routing resources.
- **DRC(Design Rule Check) Prediction:** This process aims to foresee which chip areas are most susceptible to violating manufacturing process design rules (Islam, 2022). It utilizes information such as component position, size, and orientation, the approximate routing paths and area occupancy of signal lines, and process design rules. Design rules themselves are a set of geometric and electrical constraints defined by the semiconductor manufacturer.
- **IR-drop Prediction:** This focuses on forecasting the voltage drop within the chip’s power delivery network, which occurs due to current flowing through resistance (I^*R). The prediction is made using the power network’s topological layout and the power consumption information of individual module units (Xie et al., 2020). It’s intrinsically linked to the chip’s instantaneous current demands across various operating modes.

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- **Thermal Prediction:** This involves predicting the regional temperature distribution of the chip during operation (Yan et al., 2025). The prediction takes into account the power consumption of various chip modules, material thermal characteristics, heat dissipation structures, and the ambient temperature in which the chip operates (Yu et al., 2025).

113 2.2 LEARNGENE
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115 Learngene represents a paradigm shift in knowledge transfer, functioning as a "neural genetic code"
 116 (Bohacek & Mansuy, 2015) to compress and preserve pre-trained insights (Feng et al., 2023). By
 117 encapsulating critical common knowledge into modular fragments, it allows descendant networks
 118 to inherit essential information efficiently, avoiding the redundancy of traditional transfer methods
 119 (Feng et al., 2024).

120 This approach offers significant advantages over conventional fine-tuning. Its modular design en-
 121 ables targeted transfer with minimal computational overhead, while Learngene-initialized models
 122 demonstrate exceptional transferability. Experiments indicate convergence speeds up to 40% faster
 123 and robust generalization in low-data regimes, matching the performance of models trained with
 124 significantly more labeled data (Wang et al., 2022).

125 Despite its success, Learngene's application remains largely confined to computer vision and NLP.
 126 This contrasts with other mainstream techniques like Knowledge Integration and Diversion (KID)
 127 (Xie et al., 2024) and WAVE (Feng et al., 2025), which continue to focus on image processing tasks.
 128 Our work aims to bridge this gap by extending the Learngene framework to the challenging domain
 129 of Electronic Design Automation (EDA).

131 3 METHODOLOGY
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133 Based on the four challenges (Knowledge Fragmentation, Feature Integration, Transferability and
 134 Scalability) in the EDA domain proposed above, we propose a novel method called TEPO to carry
 135 out the migration of EDA prediction tasks.

137 3.1 MULTIMODAL FUSION
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139 For Graph Neural Network (GNN) models, they excel at capturing the topological features of a chip,
 140 including the relative positions and connectivity of nodes. However, GNNs often fall short in fully
 141 extracting the logical relationships of features and tend to overlook the underlying structure of the
 142 netlist (Ren et al., 2022; Ma et al., 2020).

143 In contrast, Vision Transformer (ViT) models are adept at capturing the geometric features of a chip,
 144 such as node positions, shapes, and orientations. Yet, ViTs lack node neighborhood information,
 145 making them less effective at capturing topological features.

147 To leverage the strengths of both, we simultaneously employ a GNN model to extract topological
 148 features and a ViT model to extract geometric features. The fusion of these two modalities yields a
 149 comprehensive fused feature that encompasses both geometric and topological information, leading
 150 to enhanced representational capabilities.

151 3.2 GNN FEATURE EXTRACTION
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153 Our approach begins by constructing a heterogeneous graph directly from the netlist, incorporating
 154 both cell and net node types. To enhance training efficiency, we partition the entire graph into several
 155 subgraphs, a strategy inspired by Circuit GNN (Yang et al., 2022) in Figure 1. The feature set for
 156 cells, nets, and their interconnections is defined as follows:

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- **Cell Features:** We capture the dimensions of each cell, represented by its width (w) and
 height (h), along with features derived from the grid location of its center point.
- **Net Features:** For each net, we record the total number of connected pins, and its maximum
 span in both the horizontal (h) and vertical (v) directions.

- **Cell-to-Cell Edge Features:** The connection between two cells is characterized by their Manhattan distance, reflecting their spatial proximity on the chip.
- **Net-to-Cell Edge Features:** Edges connecting a net to a cell are characterized by the precise x/y coordinates of the pin that establishes the connection.

We will perform Linear Projection on the features of the graph, using a fully connected layer to project the feature vectors of different nodes onto a fixed-size dimension D . Subsequently, the projected results are input into the information between the HeteroGraphConv (Yang et al., 2022) fusion nodes, which includes:

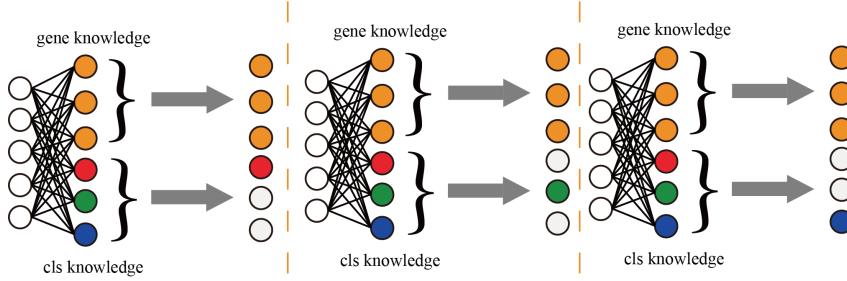


Figure 2: Learngene is applied to various types of downstream tasks.

1. **CFCNN:** This component is responsible for aggregating information from nets onto cells, effectively enriching cell representations with net-level context.

$$h_i^{(l+1)} = W_{\text{out}}^{(l)} \left(h_i^{(l)} + \sum_{j \in \mathcal{N}(i)} (W_{\text{in}}^{(l)} h_j^{(l)}) \odot \text{MLP}^{(l)}(e_{ij}) \right) \quad (1)$$

where $h_i^{(l)}$ represents the cell representation at layer l , $W_{\text{out}}^{(l)}$ and $W_{\text{in}}^{(l)}$ are the output and input weight matrices at layer l respectively, $\mathcal{N}(i)$ denotes the neighbors of cell i , e_{ij} is the edge feature from cell i to cell j , $\text{MLP}^{(l)}$ is the Multi-Layer Perceptron at layer l , and \odot denotes element-wise multiplication.

2. **SAGEConv:** To capture inter-cell relationships, SAGEConv enables information exchange directly between cells, allowing them to learn from their topological neighbors.

$$h_i^{(l+1)} = W^{(l)} \left(h_i^{(l)} \left\| \frac{1}{|\mathcal{N}(i)|} \sum_{j \in \mathcal{N}(i)} h_j^{(l)} \right\| \right) \quad (2)$$

where $\|$ denotes the concatenation operation.

3. **GraphConv:** Conversely, GraphConv aggregates cell-specific information onto nets, ensuring nets are informed by the characteristics of the cells they connect.

$$h_i^{(l+1)} = \sigma \left(\text{BN}^{(l)} \left(W_1^{(l)} \cdot h_i^{(l)} + W_2^{(l)} \cdot \sum_{j \in \mathcal{N}(i)} e_{ji} \cdot h_j^{(l)} \right) \right) \quad (3)$$

where σ represents a nonlinear activation function. $\text{BN}^{(l)}$ stands for Batch Normalization at layer l . It normalizes the inputs of a layer by re-centering and rescaling them.

Finally, a Flatten by Position operation is applied. This critical step strategically places the learned features of each node onto their corresponding spatial locations within a unified Feature Map, preparing the data for subsequent processing.

3.3 ViT FEATURE EXTRACTION

We utilize a 256×256 feature map to represent node information. This process begins with Patch Embedding, which involves dividing the input ViT grid map into fixed-size patches. Each resulting patch is then augmented with positional embeddings. These patches are subsequently linearly

216 projected into a fixed-dimensional space, forming a patch sequence. This patch sequence is then
 217 processed through a stack of multiple ViT Encoder layers to extract geometric features.
 218

219 The GNN’s feature space is projected onto the ViT’s 256×256 feature map. To align the ViT’s patch
 220 features with the GNN’s node features, a feature difference loss is employed, which supervises
 221 the model’s learning for the prediction task. These integrated features then serve as input for the
 222 downstream model.

223 3.4 GENERATION AND EXTRACTION OF LEARNGENE

226 In the TEPO framework, we introduce a novel knowledge gene extraction mechanism that decom-
 227 poses the traditional weight matrix $W \in \mathbb{R}^{d_{out} \times d_{in}}$ into two semantically meaningful components:
 228 gene knowledge and class knowledge. This decomposition is based on Singular Value Decomposi-
 229 tion (SVD), a technique that factors a matrix into three components, $W = U\Sigma V^T$, where U and V are
 230 orthogonal matrices and Σ is a diagonal matrix containing the singular values in descending order.
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232 We leverage the property of singular values to separate universal and task-specific knowledge. The
 233 singular values in Σ represent the importance of each component. By partitioning these values, we
 234 can obtain two low-rank approximations of the original weight matrix.

$$235 \quad W_{gene}^{(l)} = U_{gene} \Sigma_{gene} V_{gene}^T \quad \text{and} \quad W_{class}^{(l)} = U_{class} \Sigma_{class} V_{class}^T \quad (4)$$

237 where l is the layer index, and the matrices are defined as follows:

- 239 • $U_{gene} \in \mathbb{R}^{d_{out} \times k_{gene}}$, $\Sigma_{gene} \in \mathbb{R}^{k_{gene} \times k_{gene}}$, and $V_{gene}^T \in \mathbb{R}^{k_{gene} \times d_{in}}$. These matrices are derived
 240 from the top k_{gene} singular values and their corresponding singular vectors. $W_{gene}^{(l)}$ represents
 241 the **gene knowledge***, which captures the most dominant and universal features of IC
 242 design.
- 243 • $U_{class} \in \mathbb{R}^{d_{out} \times k_{class}}$, $\Sigma_{class} \in \mathbb{R}^{k_{class} \times k_{class}}$, and $V_{class}^T \in \mathbb{R}^{k_{class} \times d_{in}}$. These are derived from the
 244 remaining k_{class} singular values and vectors. $W_{class}^{(l)}$ represents the class knowledge, which
 245 captures the less dominant but task-specific information.

247 The effective weight matrix for a given layer is then the sum of these two components, as expressed
 248 in Equation (3).

$$251 \quad W_{effective}^{(l)} = W_{gene}^{(l)} + W_{class}^{(l)} \quad (5)$$

253 This approach ensures that the decomposition is not arbitrary but is based on the inherent structure
 254 of the weight matrix, thereby addressing the identifiability concern raised by the reviewer.

255 The diagonal elements of the matrix Σ , known as singular values, are ordered in descending magni-
 256 tude. These singular values mathematically represent the most significant to least significant infor-
 257 mation components within the matrix (Strang, 2012). Our approach leverages this property of SVD
 258 to ensure the uniqueness and semantic meaning of the decomposition. Specifically, we first perform
 259 an SVD on the original 768×768 -dimensional weight matrix W . We then partition the knowledge
 260 based on the singular values in Σ :

261 Gene Knowledge: We construct the matrix by extracting the top 512 largest singular values from
 262 the diagonal matrix Σ and multiplying them with their corresponding U and V matrices. Since these
 263 largest singular values represent the most dominant and general information within the matrix W ,
 264 we define them as the "gene knowledge" shared across all tasks.

265 Class Knowledge: Correspondingly, we use the remaining 256 singular values to construct the ma-
 266 trix. These smaller singular values represent the less dominant, more specific information, which
 267 we define as the task-specific "class knowledge."

268 By strictly partitioning based on the magnitude of the singular values, we assign a clear semantic
 269 role to both $W_{gene}^{(l)}$ and $W_{class}^{(l)}$: $W_{gene}^{(l)}$ captures general patterns, while $W_{class}^{(l)}$ captures specific details.

270 3.5 INHERITANCE OF LEARNGENE
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272 In the preceding step, we have successfully saved the pre-trained weight parameters for both gene
273 knowledge and class knowledge models. These pre-trained weights serve as the cornerstone for sub-
274 sequent model adaptation and task-specific fine-tuning, encapsulating a wealth of learned patterns
275 and features from the initial training phase. When confronted with downstream tasks, a strategic
276 approach is adopted for model initialization. Gene knowledge embodies fundamental biological and
277 genetic principles that are often transferable across various related tasks. By leveraging pre-trained
278 gene knowledge, the model can start from a more informed state, reducing the amount of data and
279 computational resources required for convergence during the training on downstream tasks.
280

281 In the scenario where existing task types are involved, based on the specific nature of the downstream
282 task type, the corresponding class knowledge is carefully selected. Different task types rely on dis-
283 tinct aspects of class knowledge, which capture task-specific semantic and structural information.
284 For tasks that fall within different categories, a sophisticated gating mechanism is employed. This
285 gating mechanism selectively activates the relevant class knowledge weight parameters while ran-
286 domly initializing the remaining parts of the class knowledge. Through this mechanism, the model
287 can focus on the most pertinent knowledge for the given task, enhancing its efficiency and perfor-
288 mance. Let the input patch sequence be $X \in \mathbb{R}^{B \times N \times d_{in}}$, where B is the batch size, N the sequence
289 length, and d_{in} the input feature dimension. The KIND linear layer decomposes transformation into
290 a shared (“gene”) path and a task-specific (“class”) path.
291

292 **Key learnable components.** We define three core quantities:
293

- 294 • The **shared scaling vector**:

$$\sigma_{\text{gene}} \in \mathbb{R}^{d_g},$$

295 which applies element-wise rescaling to the shared low-rank subspace.
296

- 297 • The **task-specific scaling vector**:

$$\sigma_{\text{class}} \in \mathbb{R}^{d_c},$$

298 which modulates importance across the task-adaptive subspace.
299

- 300 • The **hard task gating vector** for task τ :

$$g_i^{(\tau)} = \begin{cases} 1, & \text{if } i \in [s_\tau, e_\tau), \\ 0, & \text{otherwise,} \end{cases} \quad \text{so that } g^{(\tau)} \in \{0, 1\}^{d_c}.$$

301 This enforces sparse activation of only the dimensions allocated to task τ .
302

303 Given projection matrices $U_g \in \mathbb{R}^{d_{in} \times d_g}$, $V_g \in \mathbb{R}^{d_g \times d_{out}}$, $U_c \in \mathbb{R}^{d_{in} \times d_c}$, and $V_c \in \mathbb{R}^{d_c \times d_{out}}$, the output
304 of the KIND linear layer is:
305

$$Y = \underbrace{(XU_g \odot \sigma_{\text{gene}})V_g}_{\text{shared path}} + \underbrace{(XU_c \odot \sigma_{\text{class}} \odot g^{(\tau)})V_c}_{\text{gated task-specific path}} + b, \quad (6)$$

306 where \odot denotes broadcasting element-wise multiplication over the (B, N) dimensions, and $b \in \mathbb{R}^{d_{out}}$
307 is an optional bias.
308

309 **Ablation: gating vs. additive mixing.** To evaluate the necessity of explicit task routing, we
310 compare against an *additive mixing* variant that removes the gating mask:
311

$$Y^{\text{add}} = (XU_g \odot \sigma_{\text{gene}})V_g + (XU_c \odot \sigma_{\text{class}})V_c + b. \quad (7)$$

312 This baseline allows all tasks to access the full class subspace, potentially causing cross-task inter-
313 ference. Our ablation study measures the performance gap between Y (gating) and Y^{add} (additive)
314 across heterogeneous multi-task settings.
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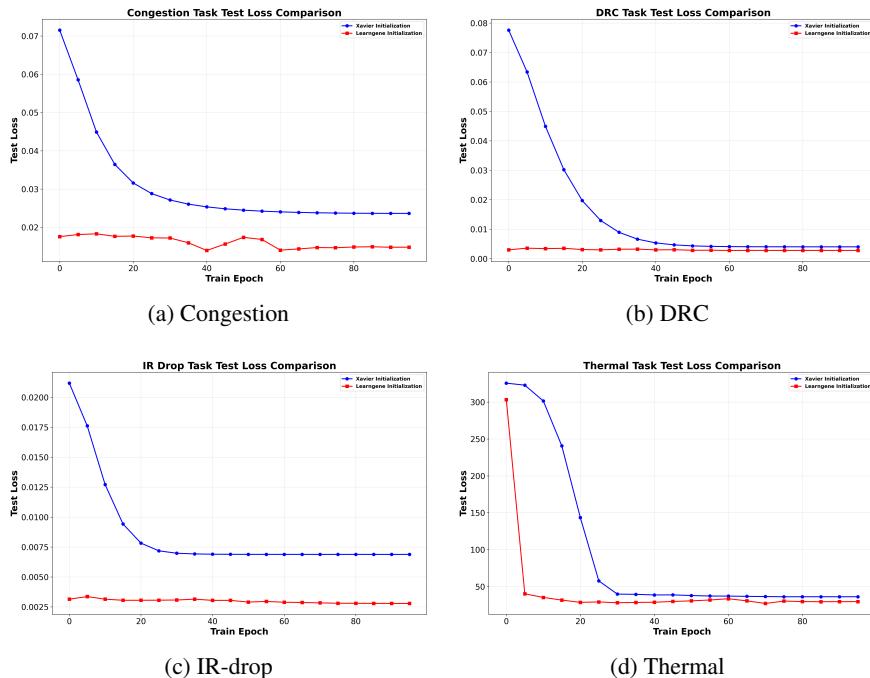
316 Conversely, when a new task type is encountered, one that has not been previously seen during
317 the training or knowledge extraction phases, only gene knowledge is used to initialize the model’s
318 weight parameters. Because gene knowledge provides a broad and general foundation that can
319 potentially adapt to novel tasks. Since no relevant class knowledge exists for the new task type, none
320

324 of the class knowledge components will be used. Instead, all dimensions of the class knowledge
 325 will be initialized randomly. This random initialization allows the model to explore and learn the
 326 unique features and requirements of the new task from scratch, while still benefiting from the initial
 327 guidance provided by the gene knowledge. This approach strikes a balance between leveraging
 328 existing knowledge and being flexible enough to accommodate unforeseen task variations, enabling
 329 the model to exhibit robust performance across a wide spectrum of downstream tasks.
 330

331 4 EXPERIMENTS

332 4.1 DATASETS

333 We conduct experiments on CircuitNet-N28 (Chai et al., 2022; Xun et al., 2024), a dataset that
 334 provides multi-modal features (image and graph) to support four cross-stage prediction tasks in
 335 back-end design: Congestion prediction, DRC (Design Rule Check) violations prediction, and IR-
 336 drop prediction. N28 refers to the 28nm planar technology. The dataset represents IC features in
 337 graph format, including: Macro Region, Cell density, RUDY (Routing Utilization and Density), Pin
 338 configuration, Congestion, DRC violations, Instance power, Signal arrival timing window and IR-
 339 drop. **The thermal prediction labels are generated through thermal simulation using hotspot, which**
 340 **can simulate the thermal labels of the chips based on the existing LEF/DEF files.**
 341



366 Figure 3: Visualization of convergence speed of TEPO and Xavier methods on downstream tasks.
 367 From the changing trend of the figure, it can be intuitively seen that TEPO has a fast convergence
 368 speed and extremely strong transferability.
 369

370 4.2 BASIC SETTING

372 First, we extract 100 samples from the CircuitNet-N28 raw data to form the training set and 20
 373 different samples to form the testing set. It should be emphasized that each sample here represents
 374 a complete IC design, and the volume of data is extremely large. Each sample contains tens of
 375 thousands of logical unit information, as well as multimodal topological and physical layout data.
 376 These lists are then fed as input to both the Vision Transformer (ViT) and Graph Neural Network
 377 (GNN) models. We set the fusion coefficient to 0.5, meaning we take half of the output from each
 378 of the ViT and GNN models for feature fusion, resulting in a 256×256 grid as the fused feature.
 379

378 For the pre-training model, we employ a 12-layer Transformer model, with the fused features serving
 379 as its input. The pre-training objectives are the congestion prediction, DRC prediction, and IR-drop
 380 prediction tasks. The sum of the losses from these three tasks is used for backpropagation.
 381

382 The downstream 12-layer Transformer task model also takes the fused features as input but operates
 383 in a single-task training mode. Specifically, it's trained for individual tasks, including: same-
 384 category tasks for Congestion, same-category tasks for DRC, same-category tasks for IR-drop, and
 385 a new task type, thermal prediction.

386 **The Key training details have been explained in the supplementary materials and can be found in the**
 387 **README file.**

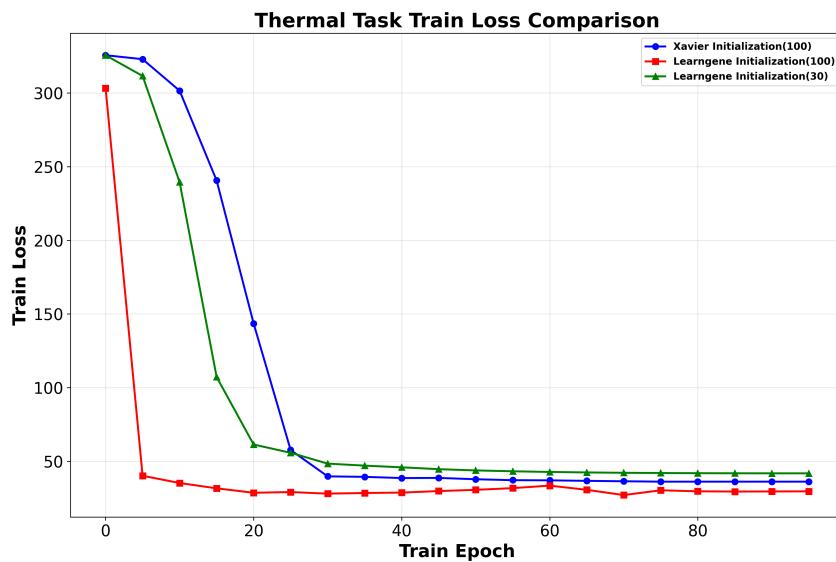
388
 389 **4.3 EVALUATION AND RESULTS**

390 We evaluate TEPO in downstream tasks using a pre-trained Learngene for model initialization, com-
 391 paring against random (Xavier) initialization and state-of-the-art EDA models.
 392

393 **Transfer Learning Setup:** We assess performance on three established tasks—congestion, DRC,
 394 and IR-drop prediction—and one novel task, thermal prediction, to test generalization beyond pre-
 395 training categories. For known tasks, both gene and class knowledge are used (with task-specific
 396 gating); for thermal prediction, only gene knowledge is activated, as no corresponding class knowl-
 397 edge exists.

Method	Congestion \downarrow	DRC \downarrow	IR-drop \downarrow	Thermal \downarrow
Xavier	0.023	0.004	0.068	36.214 °C
TEPO	0.014	0.002	0.027	29.933 °C

403 Table 1: TEPO uses Learngene for weight initialization, whereas Xavier adopts random weight
 404 initialization. This is reflected in their final performance on downstream tasks, with the evaluation
 405 metrics being Mean Squared Error (MSE) and Celsius degrees.



426 Figure 4: For the Thermal task, Learngene uses 100 and 30 training data respectively, while Random
 427 uses 100 training data.

428 **Convergence and Performance:** As shown in Figure 3 and Table 1, TEPO achieves significantly
 429 faster convergence than Xavier initialization across all tasks. On congestion, DRC, and IR-drop,
 430 TEPO reaches near-optimal performance within few epochs, while Xavier requires substantially
 431 more iterations. For the unseen thermal task, TEPO converges approximately 75% faster despite

432 lacking task-specific class knowledge, demonstrating strong transferability through learned universal
 433 design patterns.

434 **Data Efficiency:** Figure 4 and Table 2 show that TEPO maintains high accuracy even under limited
 435 training data (e.g., 50% or 30% of full set), outperforming Xavier by large margins, especially in
 436 low-data regimes.

437 **Comparison with SOTA Models:** In end-to-end performance (Table 3), TEPO surpasses existing
 438 EDA models including CircuitNet (GPDL, RouteNet), NetlistGNN, GCN, GAT, and SAGE, vali-
 439 dating the effectiveness of Learngene-based initialization and multi-modal fusion.

440 In addition, we present the specific data of the trained models in Table 1, showing that TEPO also
 441 achieved performance improvements: the accuracy of the Congestion prediction task was improved
 442 by approximately 39.13%, DRC by about 50%, IR-drop by around 60.29%, and Thermal by roughly
 443 17%.

444 In Figure 4, we trained the model using varying amounts of training data for new task type (Thermal
 445 prediction). Notably, with merely 30 training data points, the TEPO method achieved predictive
 446 accuracy comparable to that of the Xavier method trained with 100 data points. This demonstrates
 447 that, due to the substantial common knowledge embedded within its Learngene, the TEPO method
 448 can reduce the required training data by approximately 70% to achieve the same level of accuracy,
 449 leading to significant savings in computational overhead. This is particularly valuable for the EDA
 450 field, where labeled data is extremely scarce. And in Table 2, the specific final performance of the
 451 models can be observed.

Method	Training Data Size	Thermal \downarrow
Xavier	100	36.214 °C
TEPO	30	41.857 °C
TEPO	100	29.933 °C

452 Table 2: The model performance achieved by TEPO and Xavier when training models with different
 453 amounts of training data. **The temperature under thermal represents the difference in temperature
 454 with the label.**

Method	Congestion \downarrow	DRC \downarrow	IR-drop \downarrow	Thermal \downarrow
GCN	0.329	0.075	0.047	44.373 °C
RouteNet	0.021	0.005	0.014	30.154 °C
NetlistGNN	0.097	0.073	0.046	41.988 °C
SAGE	0.327	0.074	0.047	44.373 °C
GPDL	0.022	0.006	0.025	38.471 °C
GAT	0.325	0.075	0.047	44.373 °C
TEPO	0.014	0.002	0.027	29.933 °C

472 Table 3: The performance of various models and TEPO was evaluated across four tasks: Conges-
 473 tion, DRC, and IR-drop, and Thermal. Prediction accuracy for Congestion, DRC, and IR-drop was
 474 measured using Mean Squared Error (MSE). For the Thermal task, prediction accuracy was quanti-
 475 fied by the error in predicted Celsius degrees.

476 To demonstrate our model’s efficacy, we conducted a comparative analysis of TEPO against the
 477 established neural network model within our dataset, as well as several other models frequently uti-
 478 lized in the Electronic Design Automation (EDA) domain, as shown in Table 1. Due to the use of
 479 learning genes, TEPO not only outperforms conventional models in convergence speed, but also,
 480 because of the application of fusion features, TEPO can extract data features more accurately and
 481 has excellent model performance. For the three previously encountered task categories: Congestion,
 482 DRC, and IR-drop, TEPO consistently achieved strong performance, proving to be fully competi-
 483 tive with traditional predictive models. Furthermore, TEPO exhibited remarkable transferability on
 484 the novel task type, Thermal. Its capacity to assimilate a significant body of common knowledge
 485 pertinent to IC (Integrated Circuit) design enabled it to deliver highly favorable results on this new

486 challenge. In contrast, other models demonstrated inherent limitations in their ability to rapidly
 487 adapt to unfamiliar tasks.
 488

489 4.4 ABLATION 490

491 To evaluate the contribution of each component in our hybrid architecture, we conduct an ablation
 492 study by comparing variants of the full model—ViT+GNN—against its individual counterparts.
 493 Specifically, we compare ViT+GNN with standalone ViT under a ViT-based backbone, and with
 494 standalone GNN under a GNN-based backbone. As shown in Table 4, when integrated with GNN,
 495 the ViT backbone achieves significantly lower IR-drop and total loss (0.03766 vs. 0.09448 for IR-
 496 drop; 0.07797 vs. 0.13304 for total loss), demonstrating that the GNN module effectively enhances
 497 physical constraint modeling. This result validate that the synergy between ViT and GNN consis-
 498 tently improves prediction accuracy.
 499

500 Backbone	501 Method	502 Congestion	503 DRC	504 IR-drop	505 Total Loss
501 ViT	ViT+GNN	0.03376	0.00655	0.03766	0.07797
	ViT	0.03218	0.00638	0.09448	0.13304
503 GNN	ViT+GNN	0.03448	0.00827	0.01660	0.05934
	GNN	0.03492	0.00698	0.01922	0.06111

506 Table 4: In the input stage of the model, the fusion features of ViT and GNN are used, or the features
 507 of either Vit or GNN are used separately for comparison on the Vit and GNN networks
 508

510 Backbone	511 Method	512 Congestion	513 DRC	514 IR-drop	515 Total Loss
511 ViT	TEPO	0.03027	0.00256	0.03219	0.06502
	MLP	0.03376	0.00655	0.03766	0.07797
514 GNN	TEPO	0.03441	0.00705	0.01608	0.05754
	MLP	0.03448	0.00827	0.01660	0.05934

516 Table 5: Both use fusion features as input. One employs MLP, while TEPO uses Learngene archi-
 517 tecture
 518

519 Furthermore, on the basis of retaining the fusion features, we used the knowledge diversion archi-
 520 tecture of TEPO for prediction. In contrast, we directly used MLP and connected three output heads
 521 for prediction. As shown in Table 5, the difference in the prediction results of our architecture is
 522 significantly smaller.
 523

524 5 CONCLUSION 525

526 This paper proposes TEPO, an innovative multi-task learning framework, aimed at addressing the
 527 increasing complexity of Electronic Design Automation (EDA) in IC (integrated circuit) design.
 528 By introducing multimodal feature fusion and Learngene, TEPO has significantly enhanced the
 529 efficiency and accuracy of EDA prediction tasks.
 530

531 The experimental results show that TEPO performs well in existing task categories, and demon-
 532 strates outstanding transferability and superior performance on new tasks such as Thermal predic-
 533 tion. Compared with traditional methods, TEPO not only achieves a faster convergence speed but
 534 also significantly reduces the amount of training data required to achieve the same performance
 535 level, thereby significantly saving computational costs.
 536

537 The proposal of TEPO has opened up new research directions for AI-driven EDA tools, especially in
 538 efficient learning by leveraging common design patterns and task-specific knowledge. Future work
 539 can explore the extension of TEPO to a wider range of EDA applications, such as physical design
 540 optimization or design space exploration, and further study its generalization ability at different
 541 process nodes and more complex chip architectures.
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